L Number	Hits	Search Text	DB	Time stamp
1	2619850	(chip die dice semiconductor ic (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO;. DERWENT; IBM_TDB	2004/10/15 15:58
2	885496	control and memory	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:58
3	42532	(stack stacked stacking stackable multilevel) with ((chip die dice semiconductor ic (integrated adj circuit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:00
4	1435264	lead leadframe (lead adj frame)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:00
5	3135	(control and memory) and ((stack stacked stacking stackable multilevel) with ((chip die dice semiconductor ic (integrated adj circuit)))) and (lead leadframe (lead adj frame))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:00
6	502306	(bond pad terminal electrode) with (both different)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:03
7	1251	((control and memory) and ((stack stacked stacking stackable multilevel) with ((chip die dice semiconductor ic (integrated adj circuit)))) and (lead leadframe (lead adj frame))) and ((bond pad terminal electrode) with (both different))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:01
8	743	wire and (((control and memory) and ((stack stacked stacking stackable multilevel) with ((chip die dice semiconductor ic (integrated adj circuit)))) and (lead leadframe (lead adj frame))) and ((bond pad terminal electrode) with (both different)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:02
9	592278	(bond pad terminal electrode wire) with (both different)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:04
10	1251	((bond pad terminal electrode wire) with (both different)) and (((control and memory) and ((stack stacked stacking stackable multilevel) with ((chip die dice semiconductor ic (integrated adj circuit)))) and (lead leadframe (lead adj frame))) and ((bond pad terminal electrode) with (both different)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:03
11	287099	(bond pad terminal electrode) and wire and "13"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:04

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| 12 | | 743 | (bond pad terminal electrode) and wire and (((bond pad terminal electrode wire) with (both different)) and (((control and memory) and ((stack stacked stacking stackable multilevel) with ((chip die dice semiconductor ic (integrated adj circuit)))) and (lead leadframe (lead adj frame))) and ((bond pad terminal electrode) with (both different)))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/15 16:05 |

L Number	Hits	Search Text	DB	Time stamp
1	2619850	(chip die dice semiconductor ic (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:58
2	885496	control and memory	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:58
3	42532	(stack stacked stacking stackable multilevel) with ((chip die dice semiconductor ic (integrated adj circuit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:00
4	1435264	lead leadframe (lead adj frame)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:00
5	3135	(control and memory) and ((stack stacked stacking stackable multilevel) with ((chip die dice semiconductor ic (integrated adj circuit)))) and (lead leadframe (lead adj frame))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:00
6	502306	(bond pad terminal electrode) with (both different)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:01
7	1251	((control and memory) and ((stack stacked stacking stackable multilevel) with ((chip die dice semiconductor ic (integrated adj circuit)))) and (lead leadframe (lead adj frame))) and ((bond pad terminal electrode) with (both different))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:01
8	743	wire and (((control and memory) and ((stack stacked stacking stackable multilevel) with ((chip die dice semiconductor ic (integrated adj circuit)))) and (lead leadframe (lead adj frame))) and ((bond pad terminal electrode) with (both different)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:02

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